

一级代理商：

深圳市弗瑞鑫电子有限公司

地址：深圳市宝安区西乡大道302号金源商务大厦B座三楼

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5. Abol e Ma im m Ra ing (Ta=25°C)

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			- 0 + 110	
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	*		0	

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6. Electrical Optical Characteristics at Ta=25°C

Parameter	Symbol	Min	T _{vj} *	Max	Unit	Condition
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		---	---			
*1.		---	10	100		
		---	---			100
		---	10	---		0
		---	00	---		0

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24-7

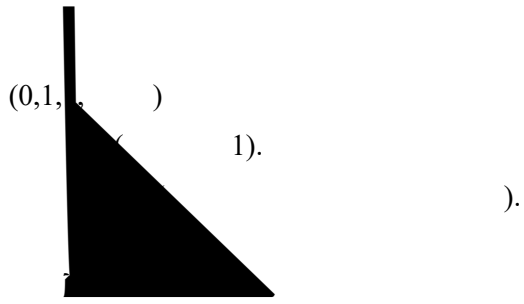
7. O de Info ma ion

Pa N mbe

OR-M302X-W-Y-Z

o OR-M305X-W-Y-Z

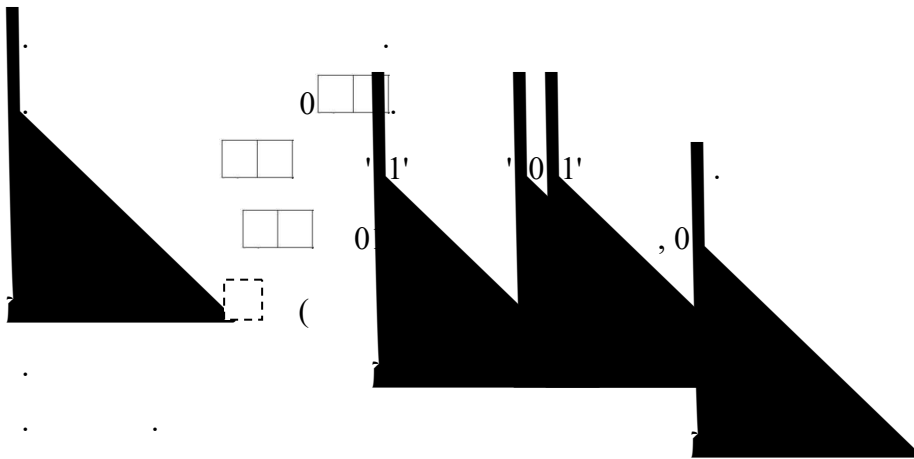
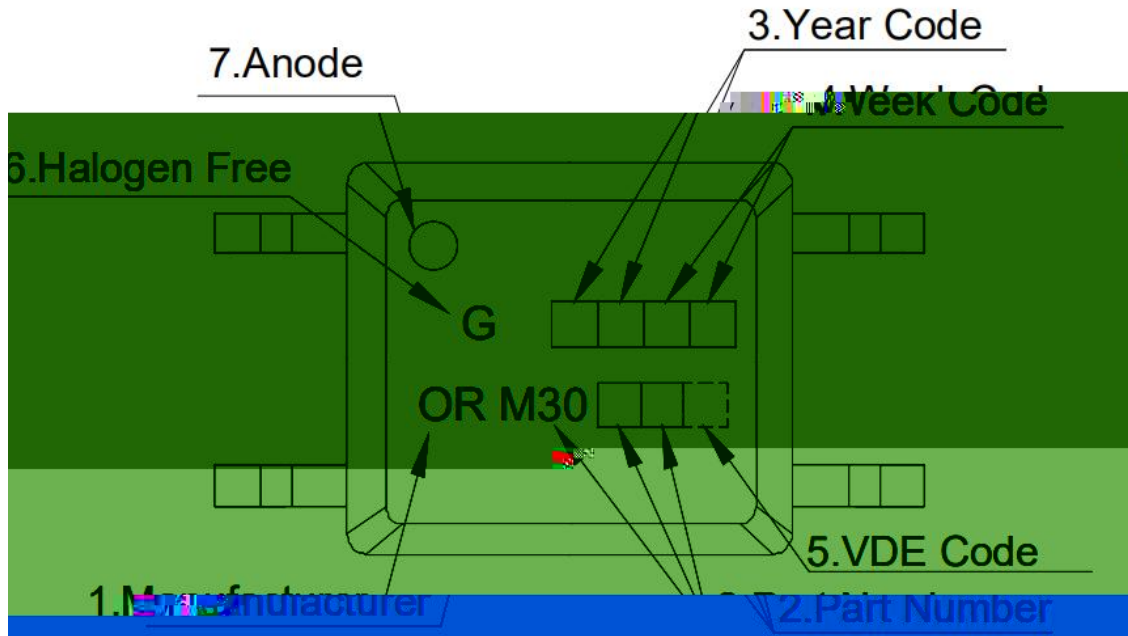
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1	()+ 1 &	000

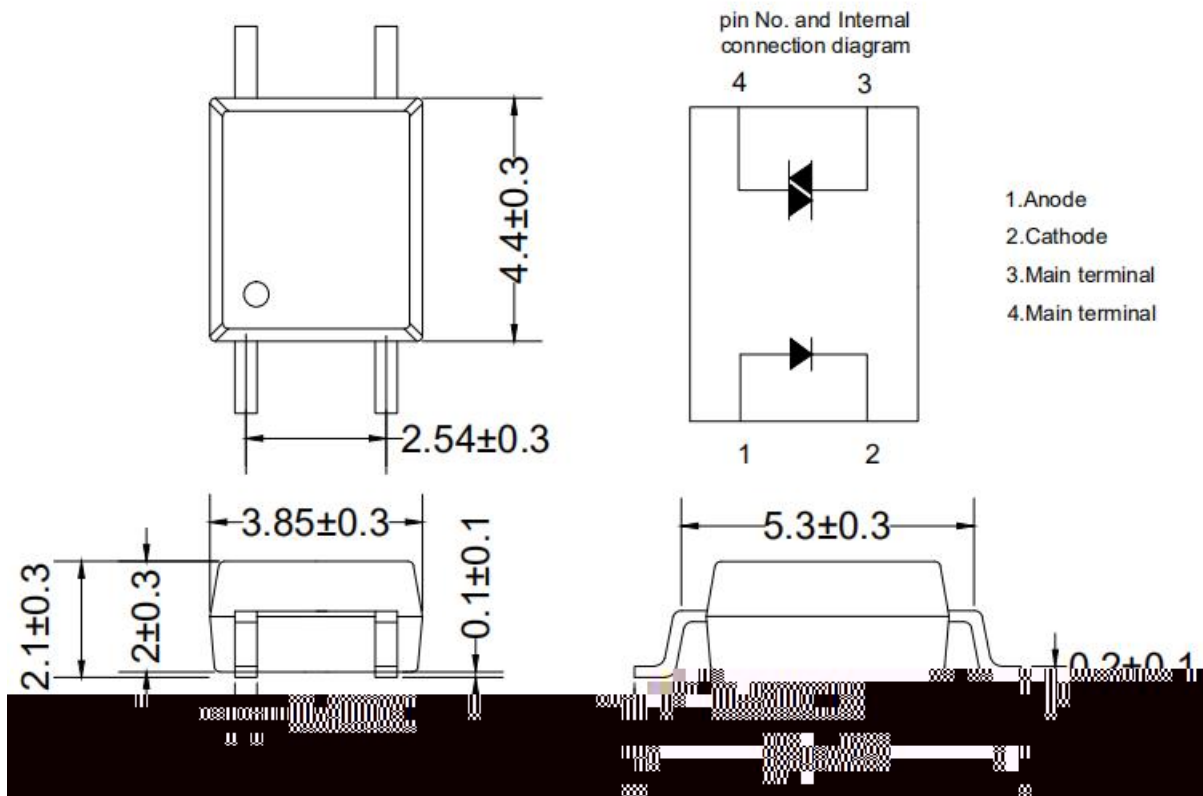
8. Naming Rule



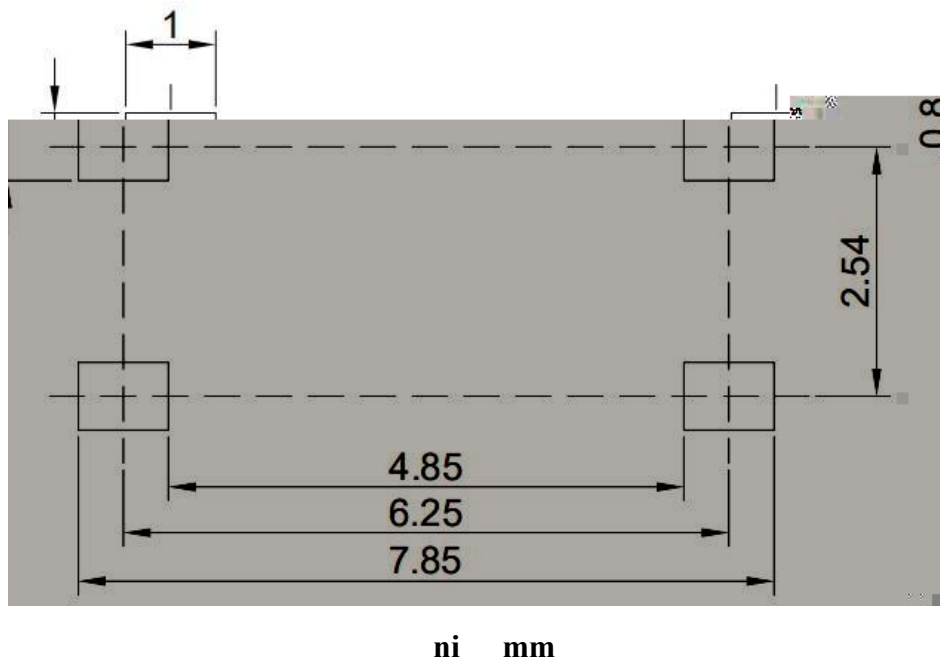
*

9. Package Dimension

- 0

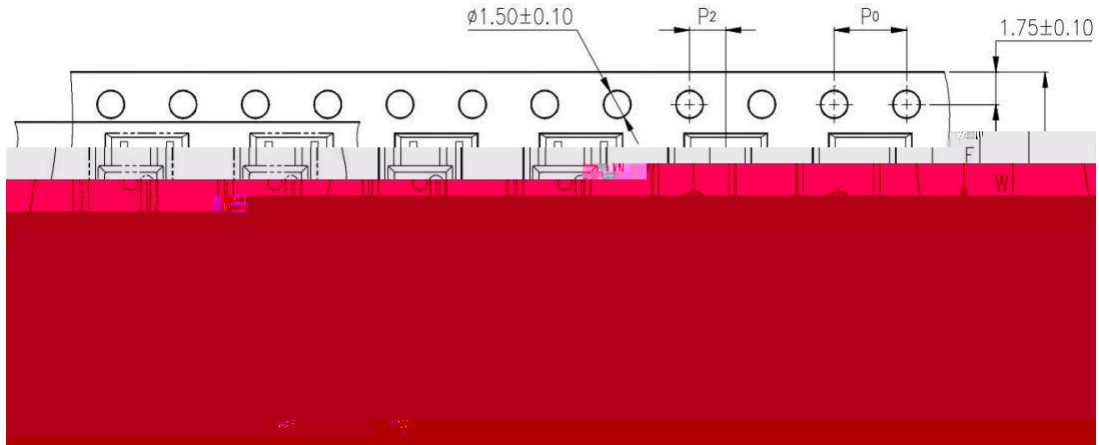


10. Recommended Foot Print in Package (Mo n Pad)

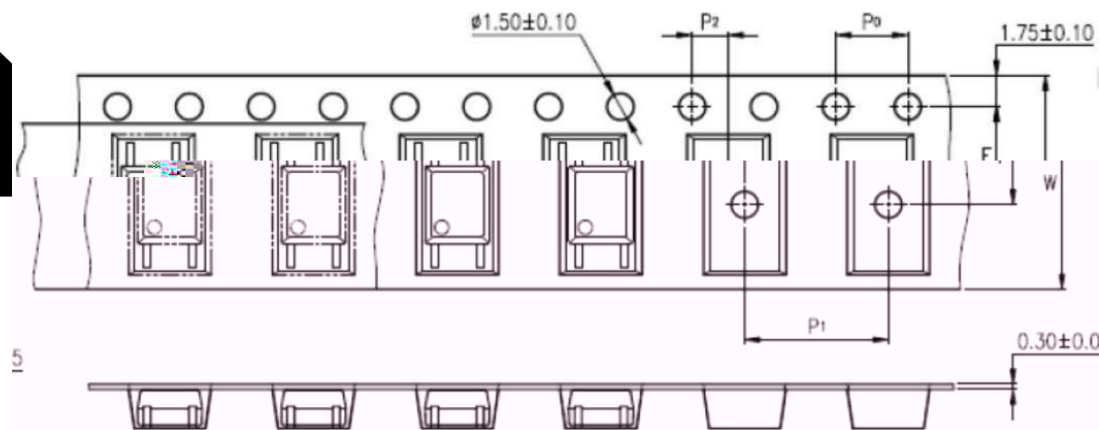


11. Ta ing Dimen ion

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		. 0.1 0.1
		0.1 0.0
	1	0.1 0. 1

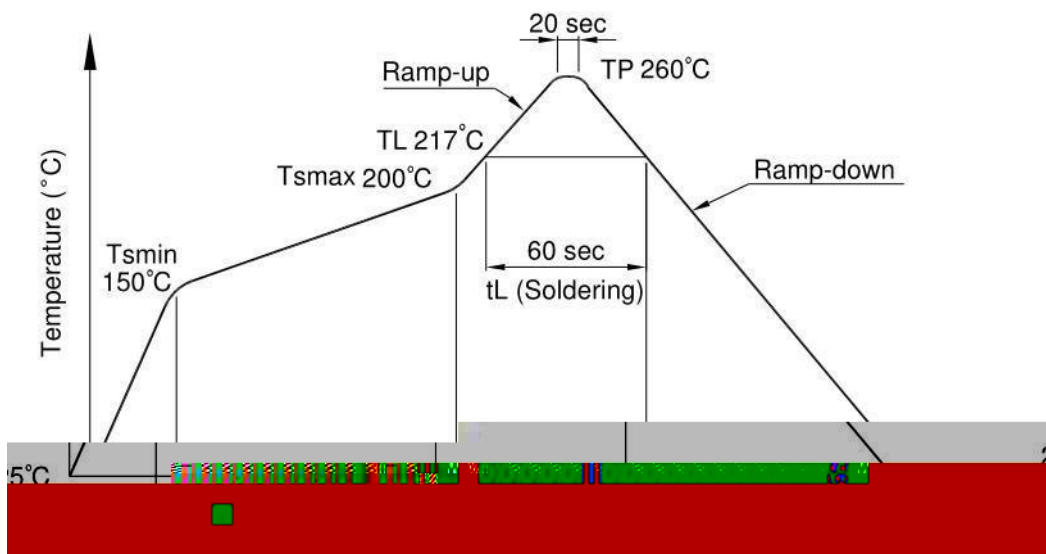
	/ 1
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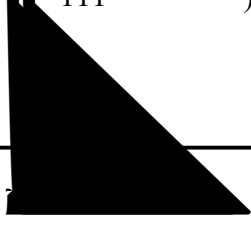
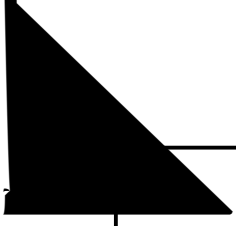
13. Temperature Profile Of Soldering

1 (- -0 0)

Profile item	Condition
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- ()	00
- () ()	0
- ()	1
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	0
	0
-	/ .
-	/



(111)



	0+0/-
	1 0
	0 0

300



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14. CHARACTERISTICS CURVES (TYPICAL PERFORMANCE)

Fig.1 Forward current vs Ambient temperature

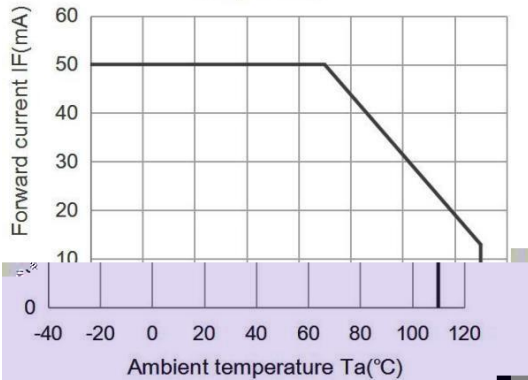


Fig.2 On-state current ITM (A) vs Ambient temperature

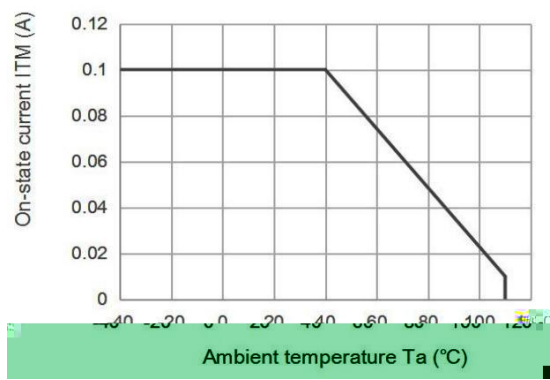


Fig.3 Minimum Trigger Current vs. Ambient temperature

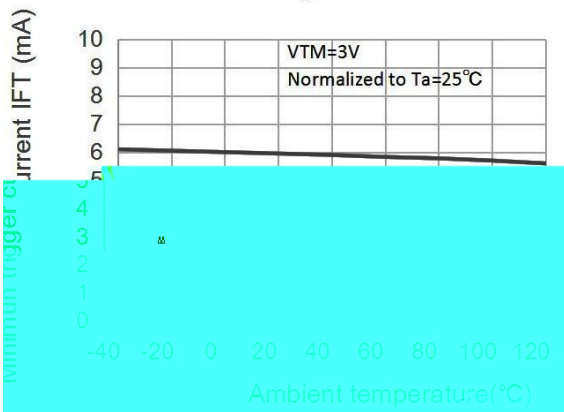


Fig.4 Forward current vs. Forward voltage

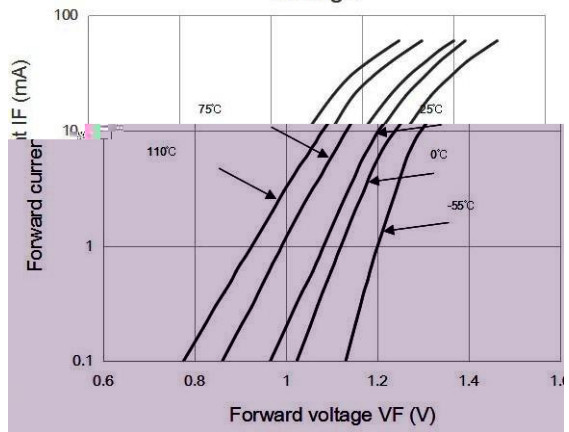


Fig.5 On-state voltage vs. Ambient temperature



Fig.6 Holding current vs. Ambient temperature

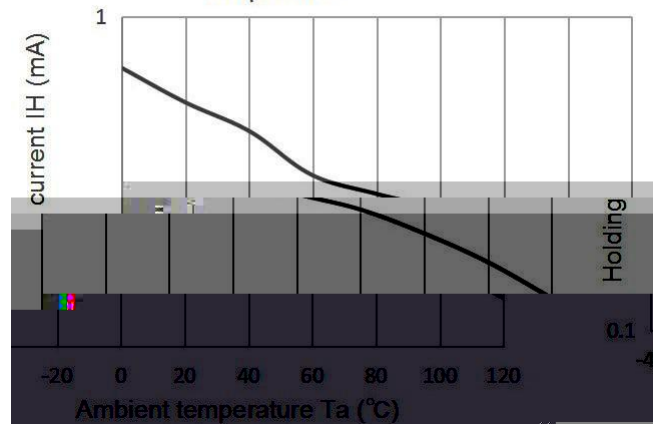


Fig.7 Repetitive peak off-state current vs. Temperature

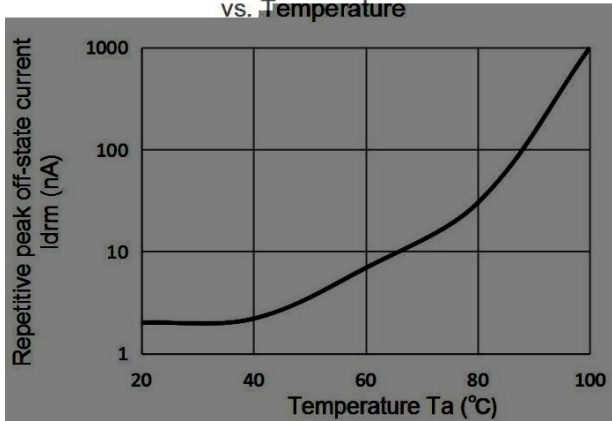
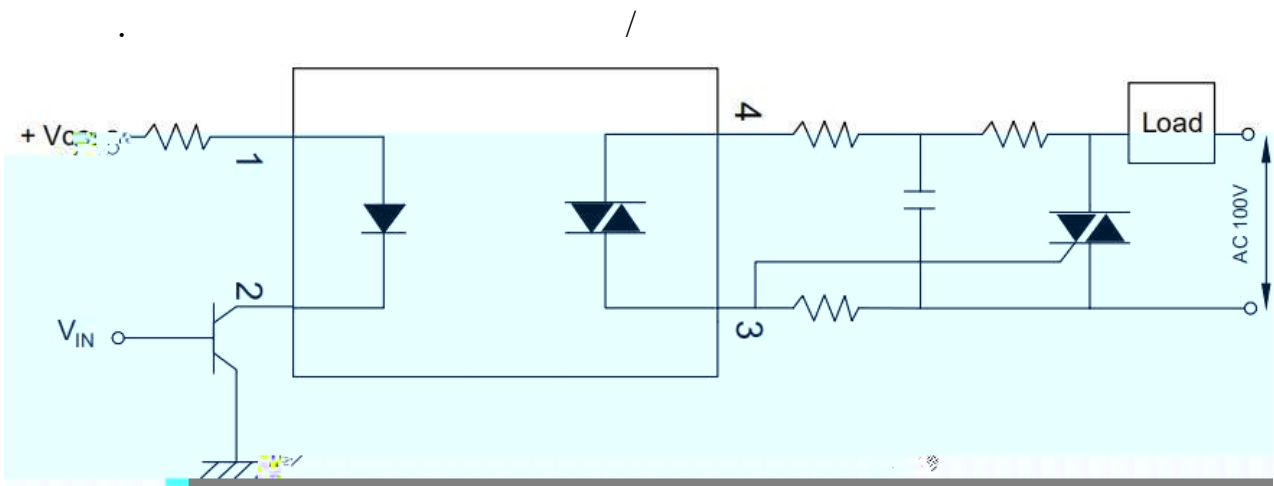
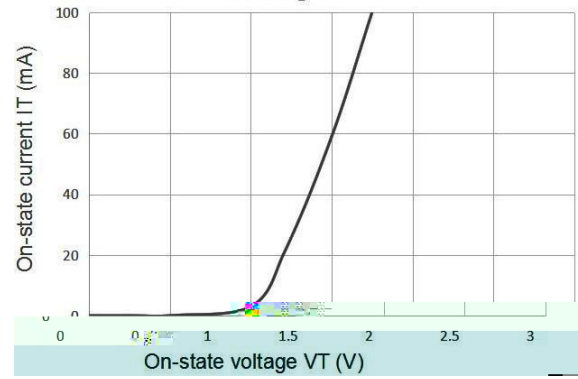
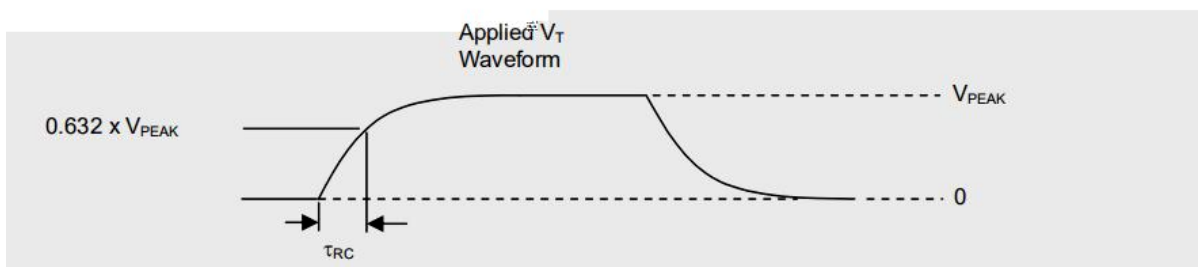
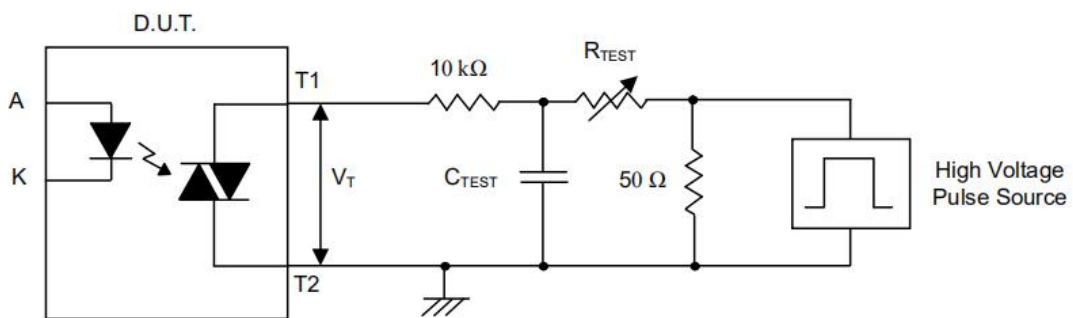


Fig.8 On-state current vs. On-state voltage



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Measurement Method

The high voltage probe is set to the nominal V_{PEAK} (e.g. 600V) using a x100 probe. By varying V_{REST}, the dv/dt (slope) is increased, until the D.U.T. is observed to trigger (waveform collapses). The dv/dt is then decreased until the D.U.T. stops triggering. At this point, τ_{RC} is recorded and the dv/dt calculated.

$$dv/dt = \frac{0.632 \times V_{PEAK}}{\tau_{RC}}$$

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For example, V_{PEAK} = 600V for EL306X series. The dv/dt value is calculated as follows:

$$dv/dt = \frac{0.63 \times 600}{\tau_{RC}} = \frac{378}{\tau_{RC}}$$